

TEMIC

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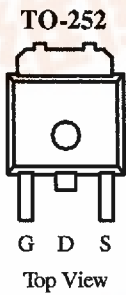
SUD/SUU40N06-24

N-Channel Enhancement-Mode Transistors

Product Summary

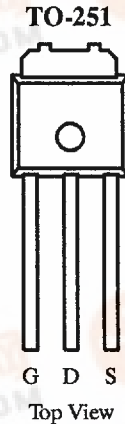
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D^a (A)
60	0.024 @ $V_{GS} = 10$ V	37

175°C Rated
Maximum Junction Temperature
TrenchFET™
Power MOSFETs

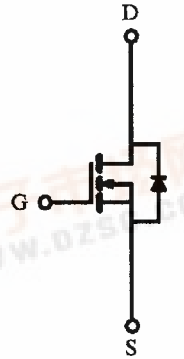


Order Number:
SUD40N06-24

Drain Connected to Tab



Order Number:
SUU40N06-24



Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_J = 175^\circ\text{C}$) ^b	I_D	$T_C = 25^\circ\text{C}$	37
		$T_C = 100^\circ\text{C}$	26
Pulsed Drain Current	I_{DM}	100	A
Continuous Source Current (Diode Conduction)	I_S	37	
Avalanche Current	I_{AR}	37	
Repetitive Avalanche Energy (Duty Cycle $\leq 1\%$)	E_{AR}	68	mJ
Maximum Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	75
		$T_A = 25^\circ\text{C}$	2.5 ^b
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 175	$^\circ\text{C}$

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	R_{thJA}		60	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Case	R_{thJC}		2.0	
Case-to-Sink	R_{thCS}	1.0		

Notes:

- a. Calculated Rating for $T_C = 25^\circ\text{C}$, for comparison purposes only. This cannot be used as continuous rating (see Absolute Maximum Ratings and Typical Characteristics).
- b. Surface Mounted on FR4 Board, $t \leq 10$ sec.



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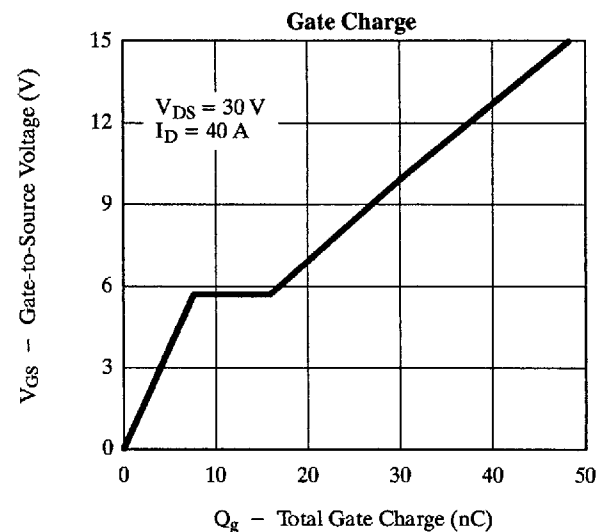
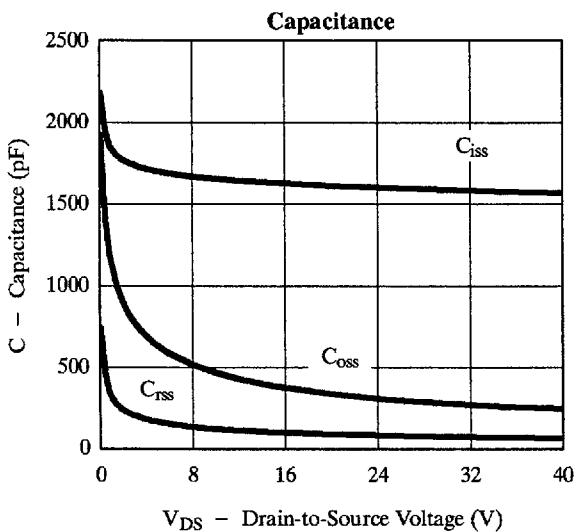
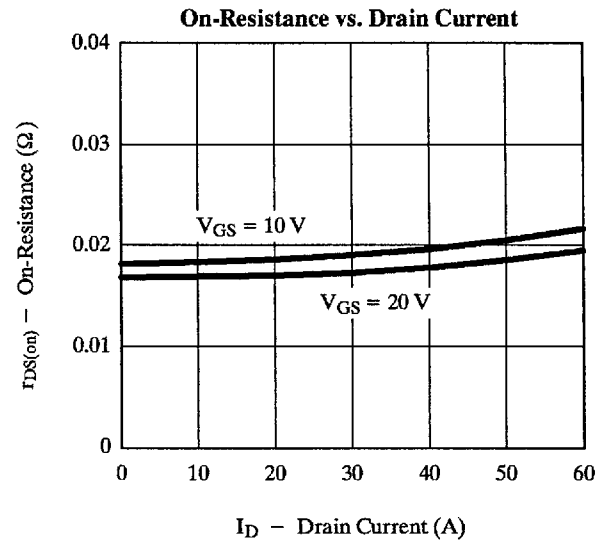
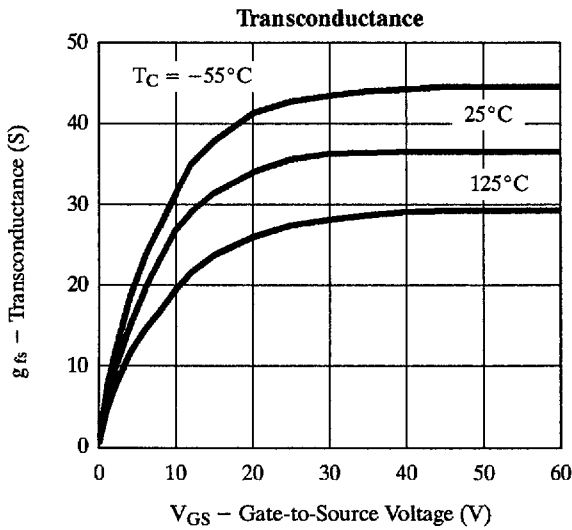
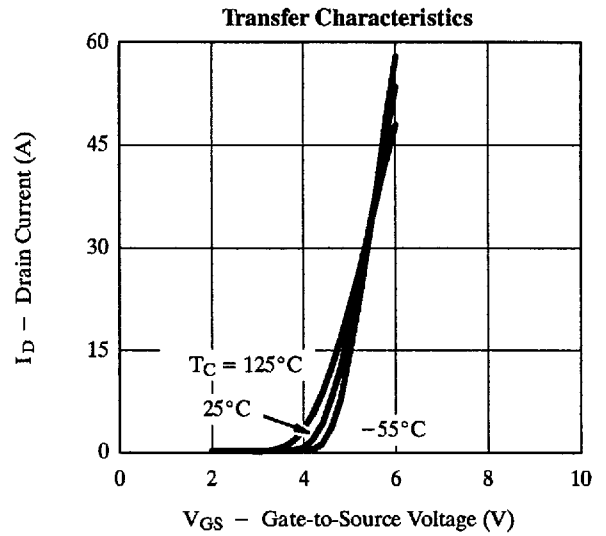
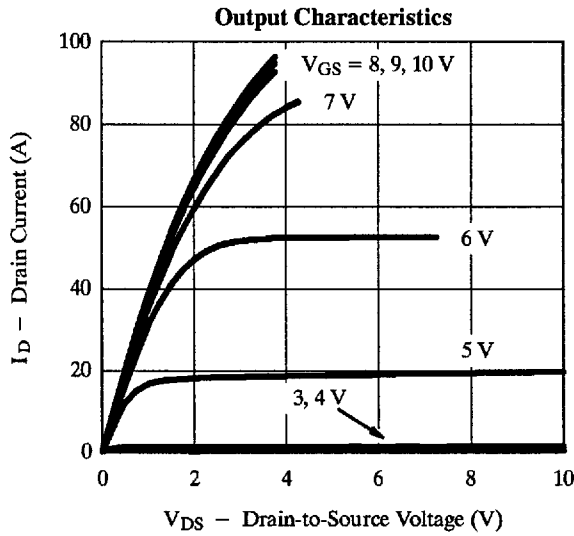
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1\ \text{mA}$	2.0	3.0	4.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$			50	
		$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}, T_J = 175^\circ\text{C}$			150	
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} = 5\text{ V}, V_{GS} = 10\text{ V}$	37			A
Drain-Source On-State Resistance ^b	$r_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 20\text{ A}$		0.020	0.024	Ω
		$V_{GS} = 10\text{ V}, I_D = 20\text{ A}, T_J = 125^\circ\text{C}$			0.044	
		$V_{GS} = 10\text{ V}, I_D = 20\text{ A}, T_J = 175^\circ\text{C}$			0.054	
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 20\text{ A}$				S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		1600		pF
Output Capacitance	C_{oss}			300		
Reverse Transfer Capacitance	C_{rss}			80		
Total Gate Charge ^c	Q_g	$V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V}, I_D = 40\text{ A}$		29	50	nC
Gate-Source Charge ^c	Q_{gs}			8		
Gate-Drain Charge ^c	Q_{gd}			8		
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 0.8\ \Omega$ $I_D = 37\text{ A}, V_{GEN} = 10\text{ V}, R_G = 2.5\ \Omega$		11	20	ns
Rise Time ^c	t_r			8	20	
Turn-Off Delay Time ^c	$t_{d(off)}$			21	40	
Fall Time ^c	t_f			7	18	
Source-Drain Diode Ratings and Characteristics ($T_C = 25^\circ\text{C}$)						
Pulsed Current	I_{SM}				37	A
Diode Forward Voltage	V_{SD}	$I_F = 37\text{ A}, V_{GS} = 0\text{ V}$		1.0	1.5	V
Reverse Recovery Time	t_{rr}	$I_F = 37\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		50	100	ns

Notes:

- For design aid only; not subject to production testing.
- Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
- Independent of operating temperature.

Typical Characteristics (25°C Unless Otherwise Noted)

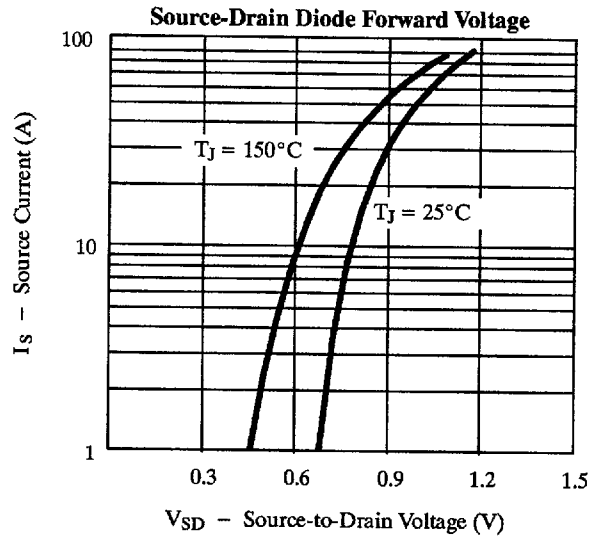
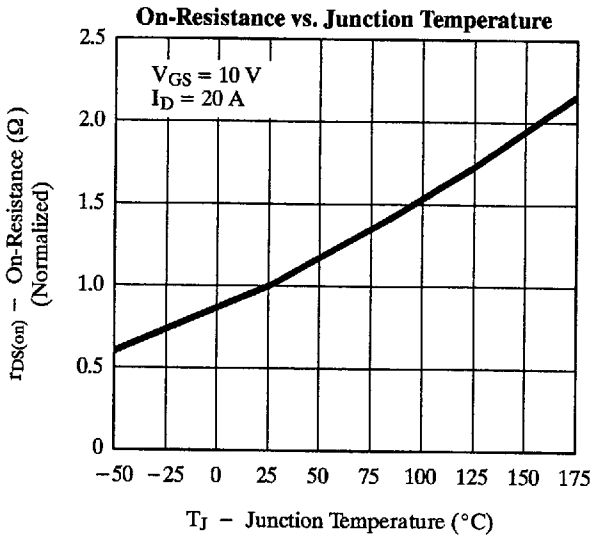


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Typical Characteristics (25°C Unless Otherwise Noted)



Thermal Ratings

